

ABSTRACT

Disclosed is a semiconductor device having a dolmen structure, including: a substrate; a first chip disposed on the substrate; a plurality of support pieces disposed around the first chip, on the substrate; and a bonding adhesive piece-attached chip supported by the plurality of support pieces and disposed to cover the first chip, in which the bonding adhesive piece-attached chip includes a second chip, and a bonding adhesive piece provided on one surface of the second chip, and a shear strength of the support pieces and the bonding adhesive piece-attached chip at 250°C is 3.2 MPa or more.

Fig. 1